

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSP298 H6327	**Issued**	11. August 2021
MA#	MA001096130		
Package	PG-SOT223-4-21	**Weight***	114.26 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.807	2.46	2.46	24563	24563
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		444	
	non noble metal	chromium	7440-47-3	0.152	0.13		1331	
	non noble metal	copper	7440-50-8	50.489	44.19	44.37	441886	443750
wire	non noble metal	copper	7440-50-8	0.015	0.01	0.01	129	129
encapsulation	organic material	carbon black	1333-86-4	0.579	0.51		5066	
	plastics	epoxy resin	-	8.683	7.60		75997	
	inorganic material	silicondioxide	60676-86-0	48.626	42.56	50.67	425582	506645
leadfinish	non noble metal	tin	7440-31-5	1.464	1.28	1.28	12813	12813
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4490	4490
glue	plastics	epoxy resin	-	0.152	0.13		1332	
	noble metal	silver	7440-22-4	0.717	0.63	0.76	6278	7610
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com